

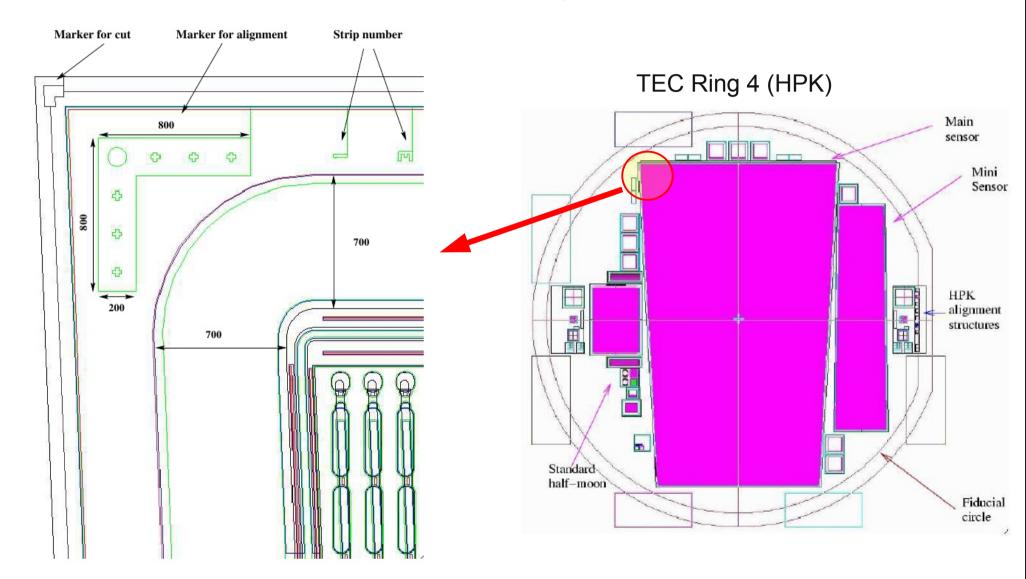


Part I

Sensors, modules, assembly



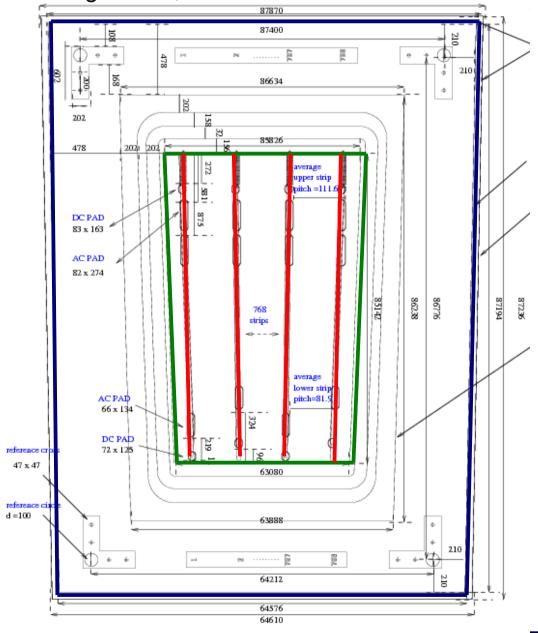
Details can be found in CMS Note 2003/020





TEC/TID sensor sketch (not to scale)

TEC ring 1 HPK, CMS Note 2003/020



- Ten(!) different sensors for TEC
- (TIB: 2, TOB: 2, TID: 1 own + 2 shared w. TEC)
- Sensor layout in reality:
 - Outer shape
 - Active area
 - Strips
 - Bonding pads
 - Bias ring
 - Guard ring
 - Alignment markers
- Outer shape and active area are trapezoids
- Strips have radial topology (i.e. constant angle between strips)



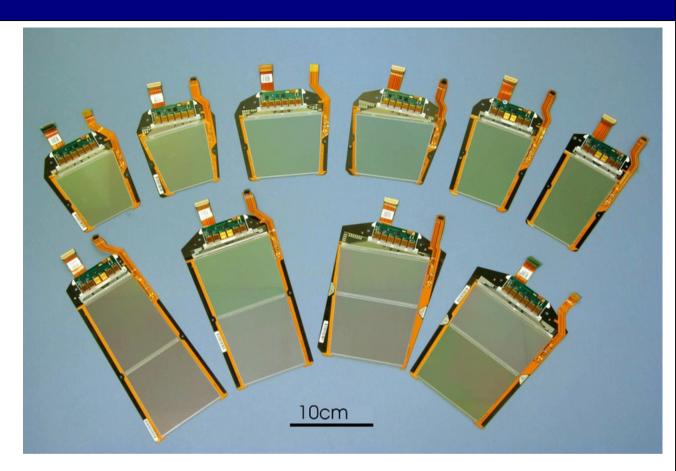
TEC sensor manufacturers and implications

- Two sensor manufacturers: Hamamatsu (HPK) and ST Microelectronics (STM)
 - Ring 1-4: HPK only
 - Ring 5-7: HPK and ST
 - Most should be HPK, only few ST. Exact position and number of ST modules is available from TrackerDB, but not known to CMSSW.
- Differences between HPK and ST:
 - Sensors active area and total area are different.
 - The ST sensor active area width or length differs by -19...28 micron depending on the sensor type. Also strips have different length.
 - Only important for efficiency studies, not for alignment
 - The thickness of the active area also differs but is a manufacturers secret
 - Will have impact on w position of sensor → already studied (B. Hoob.)
- Equivalent angular width and strip positioning for ST and Hamamatsu
 - According to e-mail conversation with Pisa group
- → In CMSSW geometry, all sensors are assumed to be HPK sensors.

TEC module layout



- Ring 1-4: single sensor
- Ring 5-7: two sensors
- Ring 1,2,5: Normal and stereo modules (sensors are the same, only different frame!)
- CMSSW description of two-sensor modules: One large sensor covering full area, no inactive zone between sensors
- Strip pitch in twosensor modules matches only if sensors exactly placed!

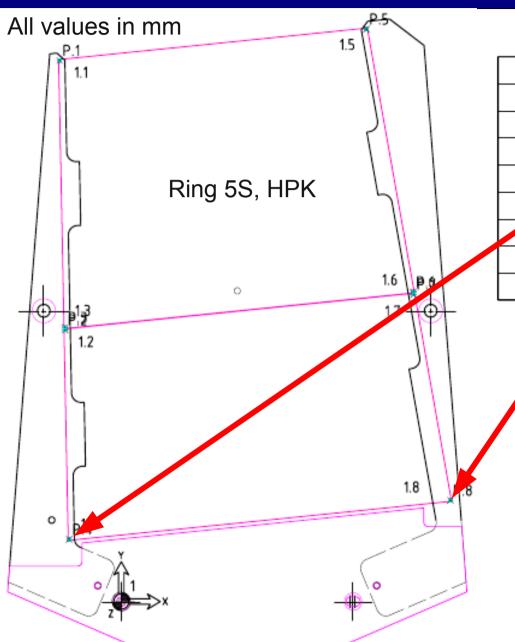


Are all two-sensors modules built in the same way?

- In principle, yes. There were exact specifications.
- Practically, no.



TEC module assembly



Nominal

Χ Pos. -19.67169,401 1.1 1.2 -17.969 85.056 85.8 1.3 -17.964 19.479 1.4 -16.615 78.215 179.222 93.151 96.949 1.6 1.7 93.304 96.221 105.005 1.8 31.682

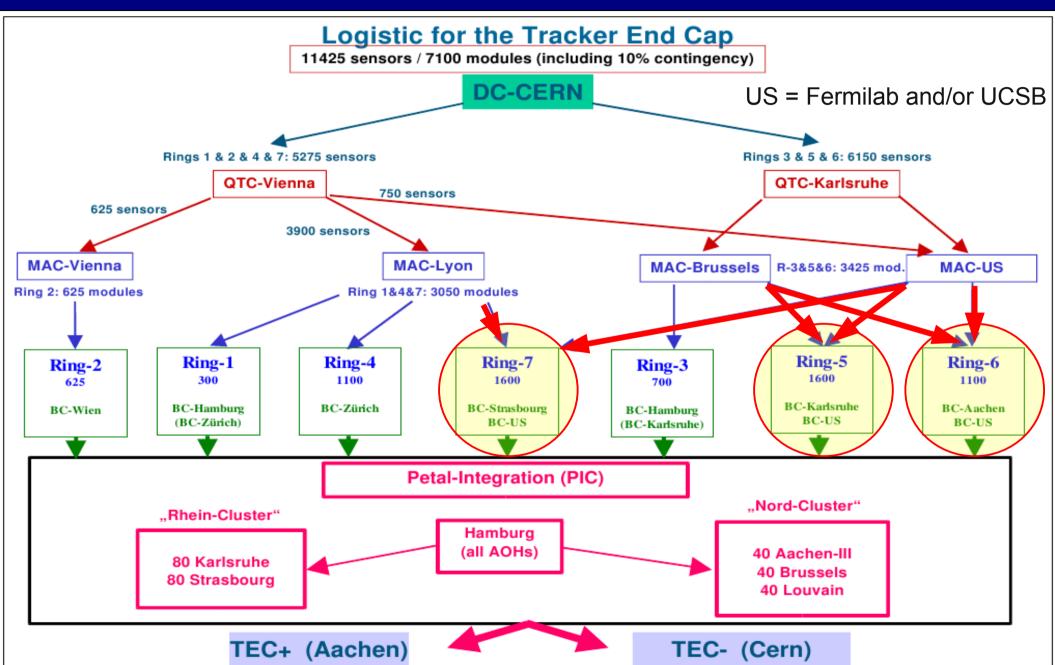
Pisa Mask Data 03.06.

Pos.	X	Y
P.1	-19.67	169.401
P.2	-17.969	85.054
P.3	-17.964	85.801
P.4	-16.567	9.484
P.5	78.214	179.223
P.6	93.151	96.95
P.7	93.304	96.219
P.8 (104.957	31.678

- First source of systematics:
 Difference between optimal placement ("pisa mask") and nominal assembly drawing
- Mostly identical values, some differences ~ few micron (i.e. below assembly precision)
- Largest Diff: Ring 5N, 5S
 Both HPK and ST versions ~50µm



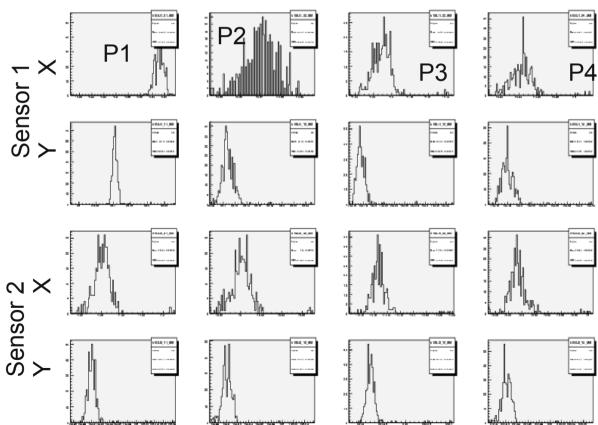
Tracker endcap assembly logistics





Did gantry centers use nominal values?

- Gantry module assembly precision ~10μm
- After module assembly (and curing of glue) sensor positions are measured by gantry
 - Extract values from TrackerDB and see if they agree with the specs
 - 25 different datasets: 10 geometries x number of gantry centers, 16 histos each



R7N_Fermilab_HPK
Small game: Compare the numbers!

(Left: Measured mean; Right: Optimal)

Sensor 1 coordinates					
	X	Υ			
P.1	70.5703	25.1085			
P.2	74.9423	134.18			
P.3	-7.2109	134.176			
P.4	-2.82912	25.1054			
Sens	sor 2 coordi	nates			
	Χ	Υ			
P.1	75.0008	134.901			
D2	78 8947	231 021			

-11.1528

-7.25882

P.3

1 001		
P.1	-11.151	231.93
P.2	-7.257	134.908
P.3	-7.204	134.168
P.4	-2.827	25.098
P.5	70.573	25.098
P.6	74.95	134.168
P.7	75.002	134.908
P.8	78.896	231.93

Pisa Mask Data 03.06.

Result: Good agreement within 10 µm

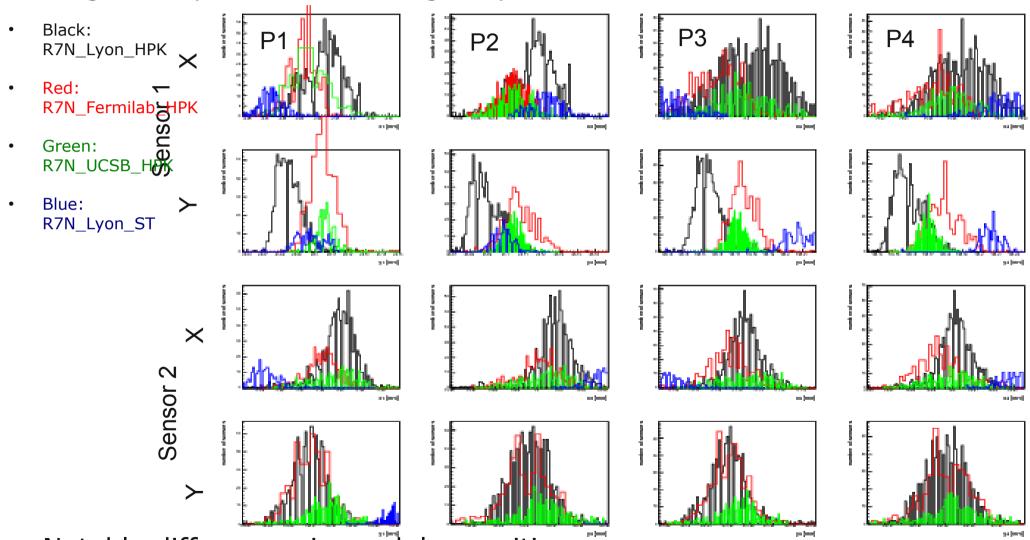
231.922

134.901



Differences between gantry centers

Ring 7 comparison between gantry centers



Notable differences in modules positions. Different for sensor 1 and sensor 2, about 10–40 μm.



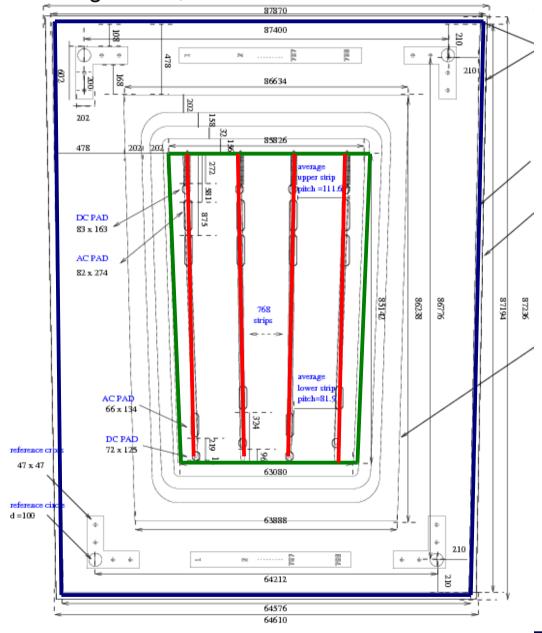
Part II

Module representation in CMSSW



TEC/TID sensor layout

TEC ring 1 HPK, CMS Note 2003/020



- Sensor layout in reality:
 - Outer shape
 - Active area
 - Strips
- Input to CMSSW geometry:
 - Outer shape
 - Active area
 - Number of strips
- In CMSSW, strip positions are calculated from number of strips and active area
- → Active area is different in reality and CMSSW simulation
 - Size is adjusted in CMSSW to reproduce correct angular pitch
 - In reality, more space next to first and last strip



Input to CMSSW geometry

1. Extract sensor values from CMS Note, put in C++ class

```
const int nRings = 16;
/** These are values from the drawings / CMS note 2003/020 */
AngularModule pisa_module[nRings] = {
  AngularModule("TEC Ring 1 HPK", 768, 0.019852, 235100, 85160, 87236, 64610, 87914),
 AngularModule("TEC Ring 2 HPK", 768, 0.01985, 323000, 88160, 90236, 88096, 112202),
  AngularModule("TEC Ring 3 HPK", 512, 0.01799, 392100, 110660, 112736, 64904, 83012),
 AngularModule("TEC Ring 4 HPK", 512, 0.012856, 504100, 115160, 117236, 59730, 73179),
 AngularModule("TEC Ring 5A ST", 768, 0.011909, 603200, 81169, 83994, 98976, 112355),
 AngularModule("TEC Ring 5B ST", 768, 0.011909, 687293, 63198, 66023, 112432, 122918),
 AngularModule("TEC Ring 6A ST", 512, 0.012847, 727000, 96136, 98961, 86100, 97385),
 AngularModule("TEC Ring 6B ST", 512, 0.012847, 826060, 84936, 87761, 97470, 107465),
  AngularModule("TEC Ring 7A ST", 512, 0.009, 888400, 106926, 109751, 74047, 82874),
  AngularModule("TEC Ring 7B ST", 512, 0.009, 998252, 94876, 97701, 82933, 90786),
  AngularModule("TEC Ring 5A HPK", 768, 0.011909, 603200, 81171, 83946, 98952, 112354),
  AngularModule("TEC Ring 5B HPK", 768, 0.011909, 687293, 63225, 65983, 112382, 122914),
 AngularModule("TEC Ring 6A HPK", 512, 0.012847, 727000, 96148, 99040, 86184, 97207),
  AngularModule("TEC Ring 6B HPK", 512, 0.012847, 826060, 84948, 87840, 97547, 107285),
 AngularModule("TEC Ring 7A HPK", 512, 0.009, 888400, 106953, 109712, 74012, 82818),
 AngularModule("TEC Ring 7B HPK", 512, 0.009, 998252, 94904, 97662, 82872, 90713)
}:
```

- 2. Extract sensor positioning values from module assembly drawings (gap between sensors in two-sensor modules)
- 3. Consistency check for two-sensor modules: Compare expected strip position with actual strip position (continuing strips from first module to second module → 10 µm syst!)



Input to CMSSW geometry (II) Validation

3. Create .xml files for CMSSW geometry description

```
<Constant name="FullHeight" value="20.7474000*cm"/>
<Constant name="ActiveHeight" value="20.4715500*cm"/>
<Constant name="DlTop" value="9.0713000*cm"/>
<Constant name="DlBottom" value="7.4012000*cm"/>
<Constant name="SideWidthTop" value="0.1376009*cm"/>
<Constant name="SideWidthBottom" value="0.1262048*cm"/>
```

4. Validate: Run CMSSW and watch creation of RadialStripTopology

```
RadialStripTopology: constructed with strips = 768 width = 3.464828e-04 rad det_height = 1.108580e+01 ctoi = 2.867290e+01 phi_edge = 1.330494e-01 rad y_ax_ori = -1 y_det_centre = 0.000000e+00

RadialStripTopology: constructed with strips = 768 width = 3.464828e-04 rad det_height = 1.108580e+01 ctoi = 2.867290e+01 phi_edge = 1.330494e-01 rad y_ax_ori = -1 y_det_centre = 0.000000e+00

RadialStripTopology: constructed with strips = 768 width = 3.464477e-04 rad det_height = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 0.000000e+00

RadialStripTopology: constructed with strips = 768 width = 3.464477e-04 rad det_height = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801e+01 phi_edge = 1.330359e-01 rad y_ax_ori = -1 y_det_centre = 8.816000e+00 ctoi = 3.670801
```

0.0000000e+00



Validation: Convert values back to input values (i.e. those from sensor drawing)

```
AngularModule "TEC Ring 1", 768, 0.019852, 235100, 85160
AngularModule "TEC Ring 1", 768, 0.019852, 235100, 85160
AngularModule "TEC Ring 2", 768, 0.019850, 323000, 88160
AngularModule, "TEC Ring 2", 768, 0.019850, 323000, 88160
AngularModule "TEC Ring 3", 512, 0.017990, 392100, 110660
AngularModule,"TEC Ring 4", 512, 0.012856, 504100, 115160
AngularModule, "TEC Ring 5", 768, 0.011909, 603200, 147262
AngularModule, "TEC Ring 5", 768, 0.011909, 603200, 147262
AngularModule, "TEC Ring 6", 512, 0.012847, 727000, 184088
AngularModule, "TEC Ring 7", 512, 0.009000, 888400, 204715
# For modulesin in rings 5,6,7 , need to compute the active length of
# two-sensor modules from pisa module table. This is the computation:
# root [1] 81171+(83946-81171)/2.+100+(65983-63225)/2.+63225
# 81171+(83946-81171)/2.+100+(65983-63225)/2.+63225
# (const double)1.47262500000000000e+05
# root [2] 96148+(99040-96148)/2.+100+(87840+84948)/2.
# 96148+(99040-96148)/2.+100+(87840+84948)/2.
# (const double)1.84088000000000000e+05
# root [3] (109712+106953)/2.+100+(97662+94904)/2.
# (109712+106953)/2.+100+(97662+94904)/2.
# (const double)2.04715500000000000e+05
```

- Validation: Compare to values from sensor drawings (page 14)
- Result: Excellent agreement within < 1 μm!

CMS UH

Summary and conclusion

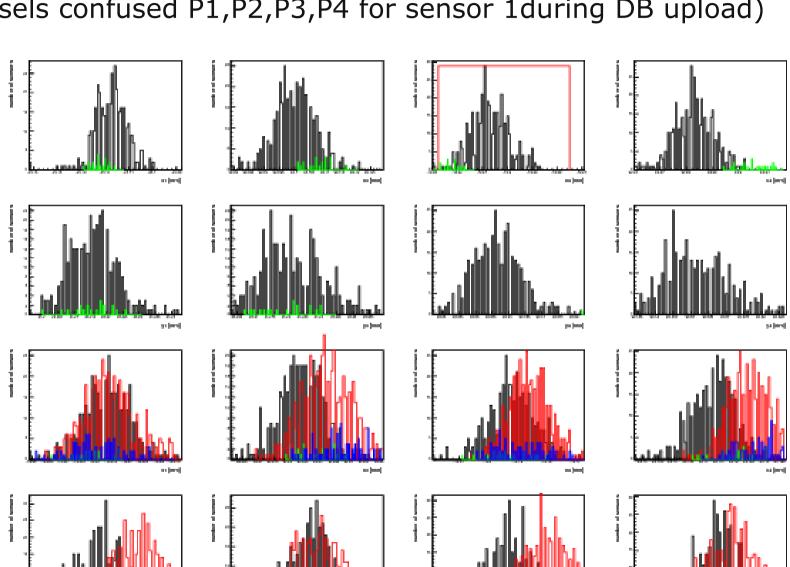
- Sensor description in CMSSW has been validated
 - Optimal description, i.e. equivalent to sensor drawings!
- Precision of module assembly has been assessed from measurements
 - Effect 1: Module drawings Some module drawings were slightly wrong, 2^{nd} sensor $\sim 50 \mu m$ in x!
 - Effect 2: Gantry implementation of module drawings
 Sometimes, wrong input values used on gantry: ~ 10 40 μm in x!
 - Effect 3: Differences between STM and HPK sensors
 Not assessed, assume everything to be HPK sensors, ~ ?? μm
 - Effect 4: Gantry precision Statistical scatter of module x with RMS \sim 10 μm
- Conclusion:
 - In principal, a complicated SQL query + math gymnastics can give precise module position of 2nd sensor
 - Experience: Better measure position with real data! (á la Claus...)
 - Also verify the strip pitch from data!



BACKUP

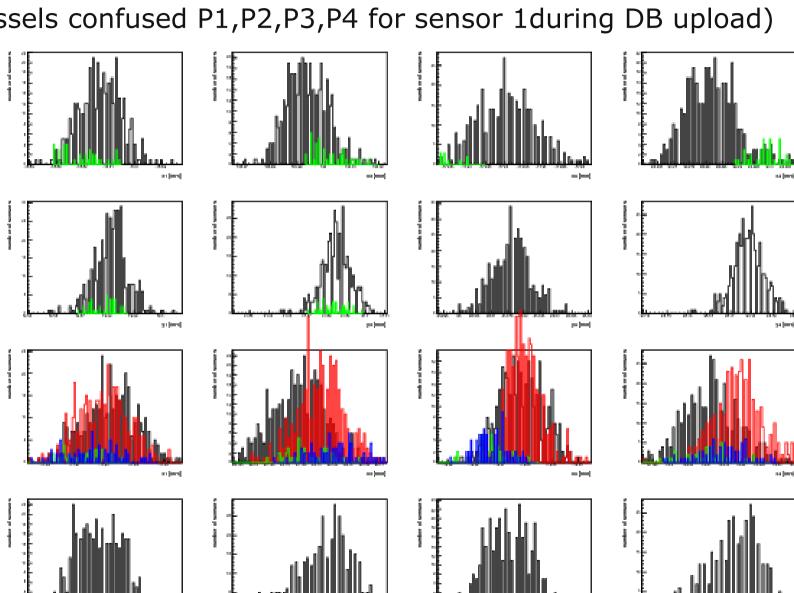


- Ring 5N (Brussels confused P1,P2,P3,P4 for sensor 1during DB upload)
- Black: **UCSB HPK**
- Red: **Brussels HPK**
- Green: **UCSB ST**
- Blue: **Brussels ST**





- Ring 5S (Brussels confused P1,P2,P3,P4 for sensor 1during DB upload)
- Black: **UCSB HPK**
- Red: **Brussels HPk**
- Green: **UCSB ST**
- Blue: **Brussels ST**





- Ring 6 (Brussels confused P1,P2,P3,P4 for sensor 1 during DB upload)
- Black: UCSB HPK
- Red: **Brussels HPK**
- Green: **Brussels LAS**

